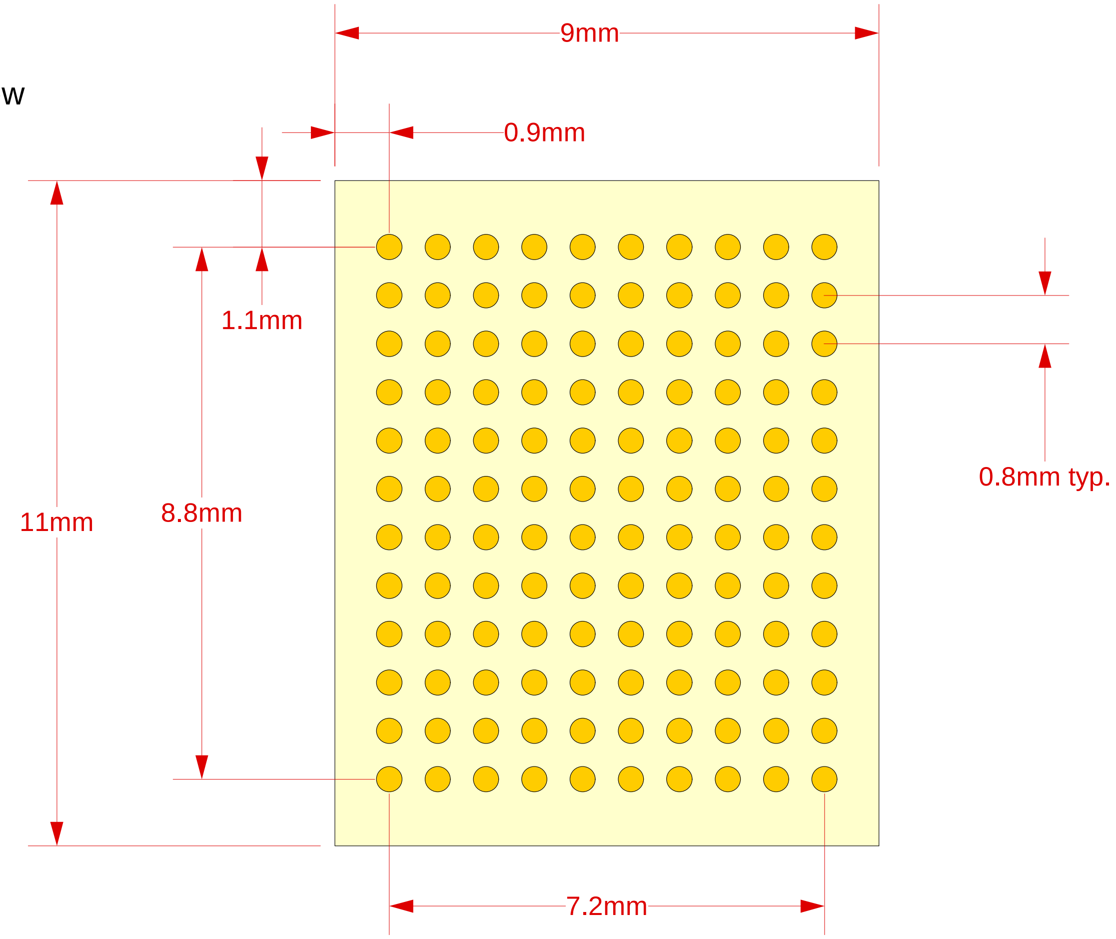
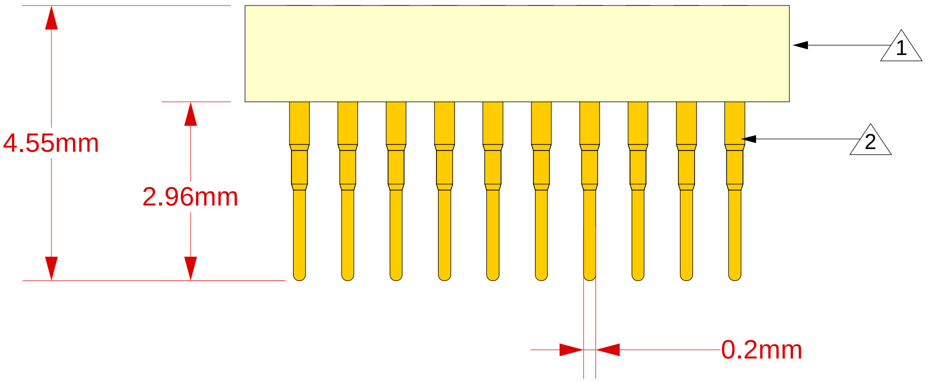
Top View



△1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. non clad

△2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Side View



Description: Giga-snaP BGA SMT Land Socket
120 position, 9mm x 11mm BGA surface mount land pattern to terminal pins (0.8mm centers, 10x12 array)

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

| | | | |
|---|---|---|---|
| **LS-BGA120G-61 Drawing** | Status: Released | Scale: 8:1 | Rev: B |
| © 2009 IRONWOOD ELECTRONICS, INC.<br>Tele: (800) 404-0204<br>www.ironwoodelectronics.com | Drawing: S. Faiz | Date: 7/6/09 | |
| | File: LS-BGA120G-61 Dwg.mcd | Modified: 01/18/13, DH | |